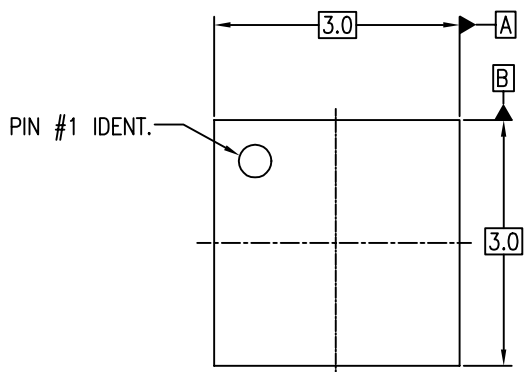
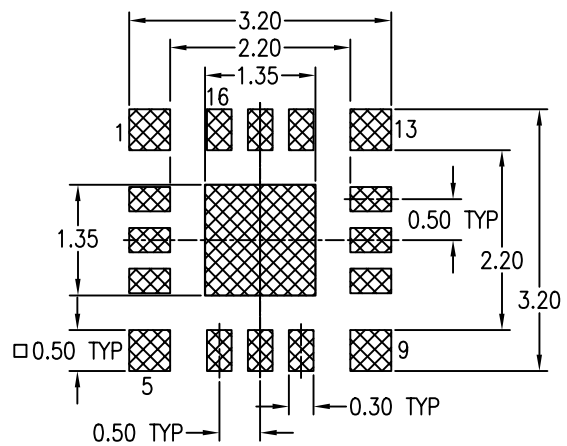


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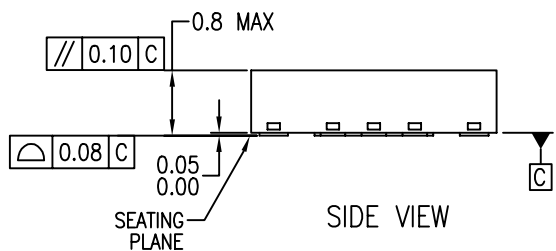
REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL		14-11-2003	FEITAN



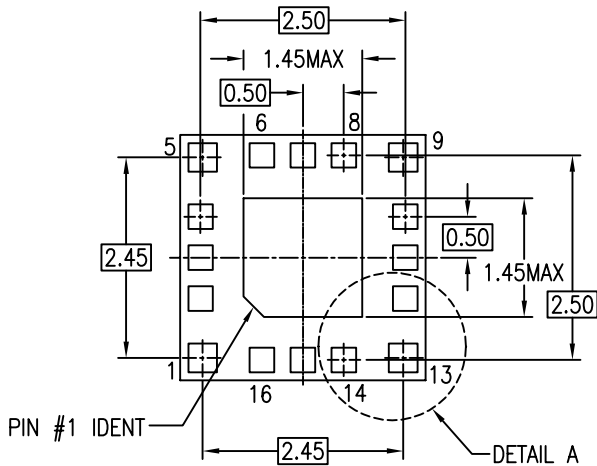
TOP VIEW



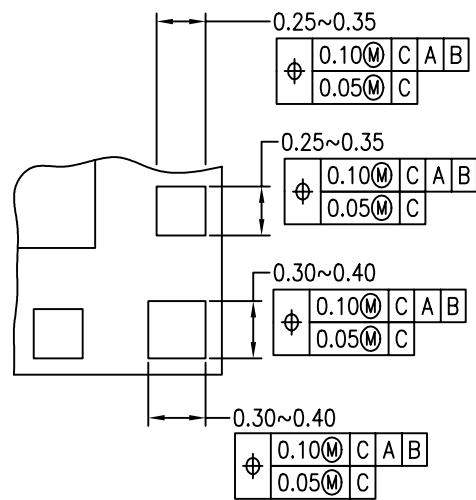
RECOMMENDED LAND PATTERN



SIDE VIEW



BOTTOM VIEW


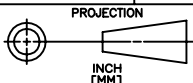


DETAIL A

NOTES:

- A. SIMILAR TO JEDEC REGISTRATION MO-217, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP16HBrevA

APPROVALS	DATE	 Bayan Lepas, FIZ, SEMICONDUCTOR 11900, Penang, Malaysia.	16LD, MLP, JEDEC MO-217 EQUIVALENT, 3MM SQUARE		
DRAWN	FEITAN 5-11-2003				
DFTG. CHK.					
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	N/A	MKT-MLP16HB	A
DO NOT SCALE DRAWING					SHEET 1 of 1